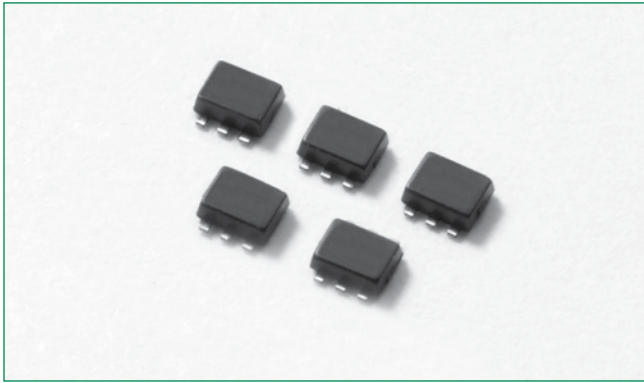
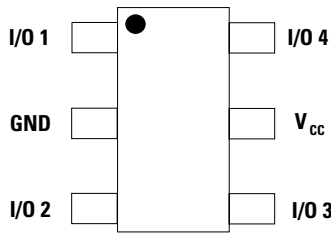


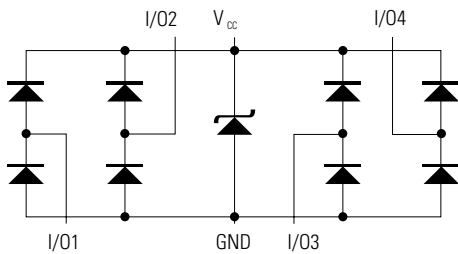
**SP3004 Series 0.85pF Diode Array**



**Pinout**



**Functional Block Diagram**



**Additional Information**



**Description**

The SP3004 has ultra low capacitance rail-to rail diodes with an additional zener diode fabricated in a proprietary silicon avalanche technology to protect each I/O pin providing a high level of protection for electronic equipment that may experience destructive electrostatic discharges (ESD). These robust diodes can safely absorb repetitive ESD strikes at the maximum level (Level 4) specified in the IEC 61000-4-2 international standard without performance degradation. Their very low loading capacitance also makes them ideal for protecting high speed signal pins such as HDMI, DVI, USB2.0, and IEEE 1394.

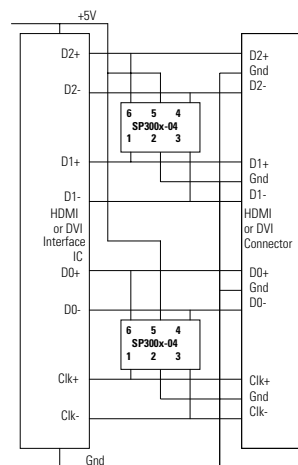
**Features**

- RoHS compliant and Lead-free
- Low capacitance of 0.85pF (TYP) per I/O
- ESD protection of ±12kV contact discharge, ±15kV air discharge, (IEC 61000-4-2)
- EFT protection, IEC 61000-4-4, 40A (5/50ns)
- Low leakage of 10nA MAX with  $V_R=3.3V$
- Small SOT563 package saves board space
- Lightning Protection, IEC 61000-4-5, 2nd Edition, 4A (8/20µs)
- AEC-Q101 qualified

**Applications**

- Computer Peripherals
- Mobile Phones
- PDA's
- Digital Cameras
- Network Hardware/Ports
- Test Equipment
- Medical Equipment

**Application Example**



A single 4 channel SP300x-04 device can be used to protect four of the data lines in a HDMI/DVI interface. Two (2) SP300x-04 devices provide protection for the main data lines. Low voltage ASIC HDMI/DVI drivers can also be protected with the SP300x-04, the +V<sub>CC</sub> pins on the SP300x-04 can be substituted with a suitable bypass capacitor or in some backdrive applications the +V<sub>CC</sub> of the SP300x-04 can be floated or NC.

Life Support Note:

**Not Intended for Use in Life Support or Life Saving Applications**

The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

### Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$I_{PP}$	Peak Current ( $t_p=8/20\mu s$ )	4	A
$T_{OP}$	Operating Temperature	-40 to 125	°C
$T_{STOR}$	Storage Temperature	-55 to 150	°C

**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### Thermal Information

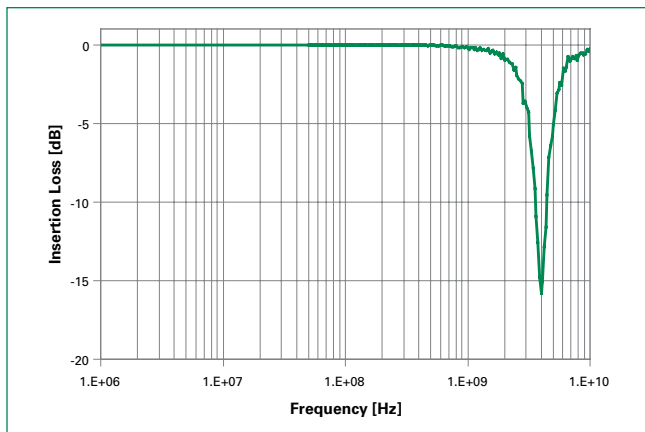
Parameter	Rating	Units
Storage Temperature Range	-55 to 150	°C
Maximum Junction Temperature	150	°C
Maximum Lead Temperature (Soldering 20-40s)	260	°C

### Electrical Characteristics ( $T_{OP}=25^\circ C$ )

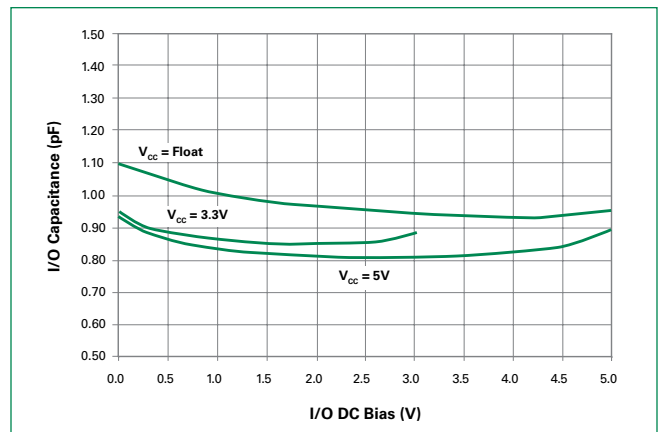
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	$V_{RWM}$	$I_R \leq 1\mu A$			6	V
Reverse Leakage Current <sup>1</sup>	$I_{LEAK}$	$V_R=3.3V$			10	nA
Clamp Voltage <sup>1</sup>	$V_C$	$I_{PP}=1A, t_p=8/20\mu s, Fwd$		10.0	12.0	V
		$I_{PP}=2A, t_p=8/20\mu s, Fwd$		11.8	15.0	V
ESD Withstand Voltage <sup>1</sup>	$V_{ESD}$	IEC 61000-4-2 (Contact)	$\pm 12$			kV
		IEC 61000-4-2 (Air)	$\pm 15$			kV
Dynamic Resistance	$R_{DYN}$	$(V_{C2} - V_{C1}) / (I_{PP2} - I_{PP1})$		1.8		$\Omega$
Diode Capacitance <sup>1</sup>	$C_{I/O-GND}$	Reverse Bias=0V	0.95	1.1	1.25	pF
		Reverse Bias=1.65V	0.7	0.85	1	pF
Diode Capacitance <sup>1</sup>	$C_{I/O-I/O}$	Reverse Bias=0V		0.5		pF

**Note:** <sup>1</sup> Parameter is guaranteed by design and/or device characterization.

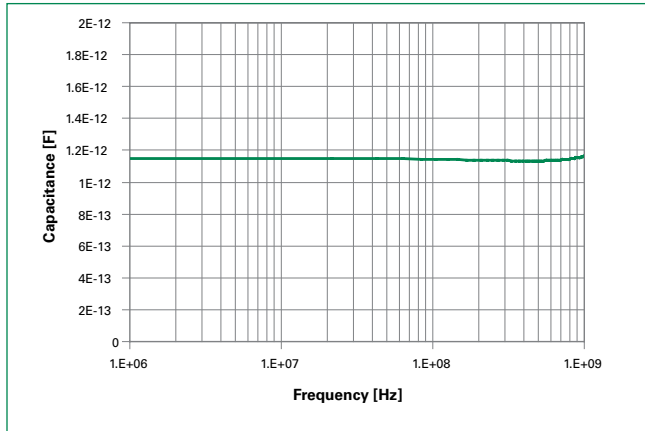
### Insertion Loss (S21) I/O to GND



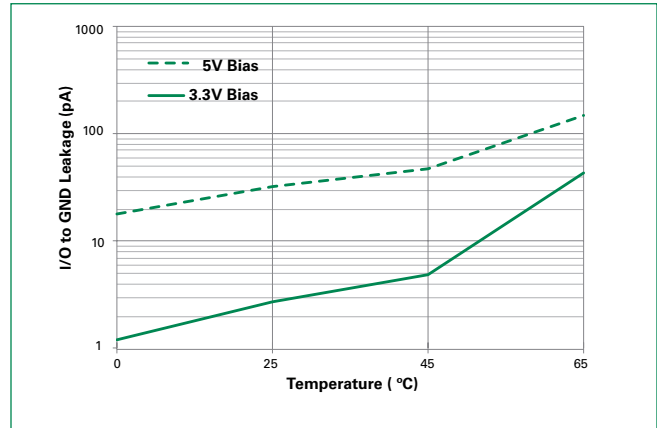
### Capacitance vs. Bias Voltage



### Capacitance vs. Frequency

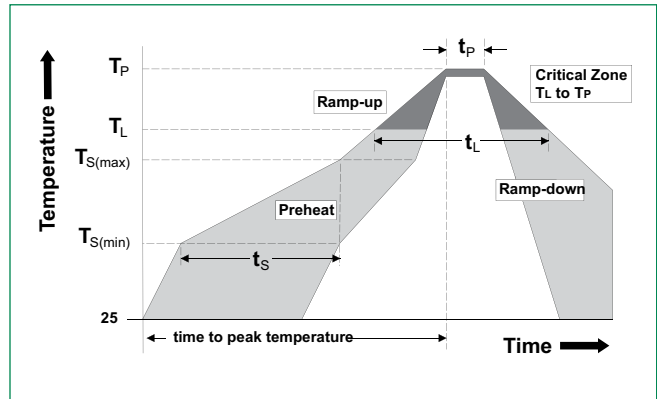


### Leakage Current vs Temperature



### Soldering Parameters

<b>Reflow Condition</b>		Pb – Free assembly
<b>Pre Heat</b>	- Temperature Min ( $T_{s(min)}$ )	150°C
	- Temperature Max ( $T_{s(max)}$ )	200°C
	- Time (min to max) ( $t_s$ )	60 – 180 secs
<b>Average ramp up rate (Liquidus) Temp (<math>T_L</math>) to peak</b>		3°C/second max
<b><math>T_{s(max)}</math> to <math>T_L</math> - Ramp-up Rate</b>		3°C/second max
<b>Reflow</b>	- Temperature ( $T_L$ ) (Liquidus)	217°C
	- Temperature ( $t_L$ )	60 – 150 seconds
<b>Peak Temperature (<math>T_p</math>)</b>		260 <sup>+0/-5</sup> °C
<b>Time within 5°C of actual peak Temperature (<math>t_p</math>)</b>		20 – 40 seconds
<b>Ramp-down Rate</b>		6°C/second max
<b>Time 25°C to peak Temperature (<math>T_p</math>)</b>		8 minutes Max.
<b>Do not exceed</b>		260°C



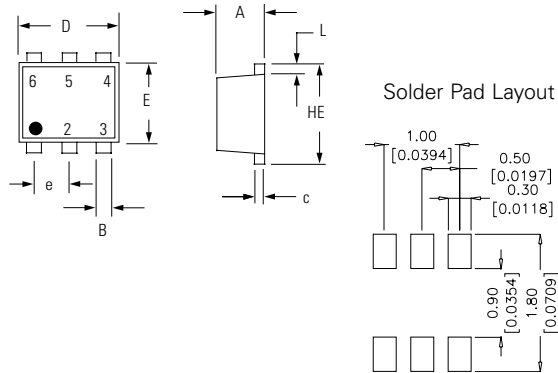
### Product Characteristics

<b>Lead Plating</b>	Pre-Plated Frame
<b>Lead Material</b>	Copper Alloy
<b>Lead Coplanarity</b>	0.0004 inches (0.102mm)
<b>Substitute Material</b>	Silicon
<b>Body Material</b>	Molded Epoxy
<b>Flammability</b>	UL 94 V-0

Notes :

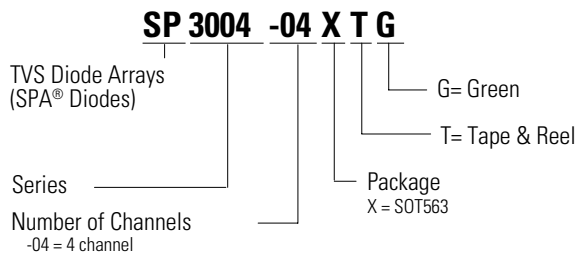
1. All dimensions are in millimeters
2. Dimensions include solder plating.
3. Dimensions are exclusive of mold flash & metal burr.
4. Blo is facing up for mold and facing down for trim/form, i.e. reverse trim/form.
5. Package surface matte finish VDI 11-13.

**Package Dimensions – SOT563**

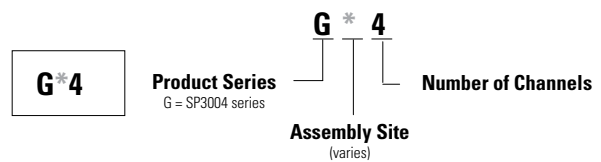


Package	SOT 563			
Pins	6			
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.50	0.60	0.020	0.024
B	0.17	0.27	0.007	0.011
c	0.08	0.18	0.003	0.007
D	1.50	1.70	0.059	0.067
E	1.10	1.30	0.043	0.051
e	0.50 BSC		0.020 BSC	
L	0.10	0.30	0.004	0.012
HE	1.50	1.70	0.059	0.067

**Part Numbering System**



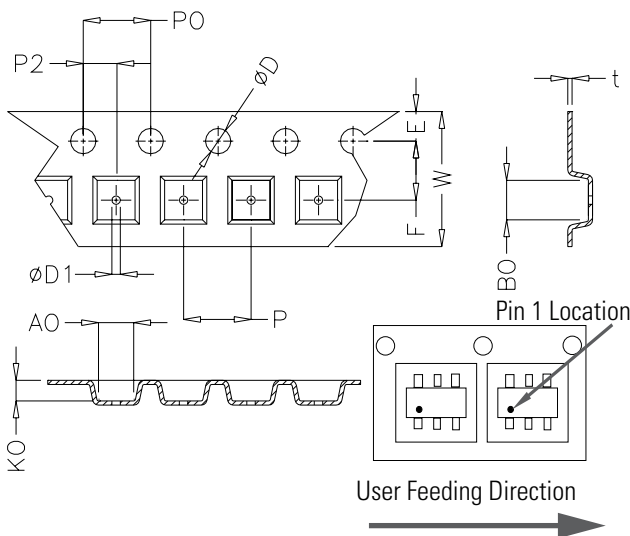
**Part Marking System**



**Ordering Information**

Part Number	Package	Marking	Min. Order Qty.
SP3004-04XTG	SOT563	G 4	3000

**Embossed Carrier Tape & Reel Specification – SOT563**



Symbol	Millimetres		Inches	
	Min	Max	Min	Max
E	1.65	1.85	0.065	0.073
F	3.45	3.55	0.135	0.139
P2	1.95	2.05	0.077	0.081
D	1.40	1.60	0.055	0.063
D1	0.45	0.55	0.017	0.021
P0	3.90	4.10	0.154	0.161
10P0	40.0±0.20		1.574±0.008	
W	7.70	8.10	0.303	0.318
P	3.90	4.10	0.153	0.161
A0	1.73	1.83	0.068	0.072
B0	1.73	1.83	0.068	0.072
K0	0.64	0.74	0.025	0.029
t	0.22 max		0.009 max	